



RSA (A/B) Series Thick Film Chip Resistors Array Product specification

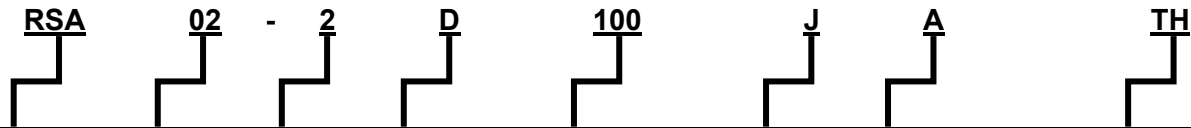
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1 Scope:

- 1.1 This specification is applicable to lead free and halogen free of ROHS directive for RSA series anti-sulfurated thick film chip resistors array.
- 1.2 Superior Sulfur resistant capability (Refer to ASTM-B-809-95&EIA977 sulfur vapor test).
- 1.3 The product is for general electronic purpose.

2 Explanation Of Part Numbers:

(EX)



Type	Size	Number of Circuits	Terminal Type	Nominal Resistance	Resistance Tolerance	FoS Test	Packaging(Refer to IE-SP-055)
Anti-Sulfurated Thick Film Chip Resistors Array	02(0402) 03(0603)	2:2circuits 4:4circuits	D:Convex	5% (3-Digit)	EX. 10Ω=100 4.7Ω=4R7 JUMPER=000	F=± 1% J=± 5%	TH : 2 mm Pitch Carrier Tape 10000 pcs H2 : 2 mm Pitch Carrier Tape 20000 pcs H3 : 2 mm Pitch Carrier Tape 30000 pcs H4 : 2 mm Pitch Carrier Tape 40000 pcs H5 : 2 mm Pitch Carrier Tape 50000 pcs TP : 4 mm Pitch Carrier Tape 5000 pcs P2 : 4 mm Pitch Carrier Tape 10000 pcs P3 : 4 mm Pitch Carrier Tape 15000 pcs P4 : 4 mm Pitch Carrier Tape 20000 pcs
				1% (4-Digit)	EX. 10.2Ω=10R2 10KΩ=1002		

3 General Specifications:

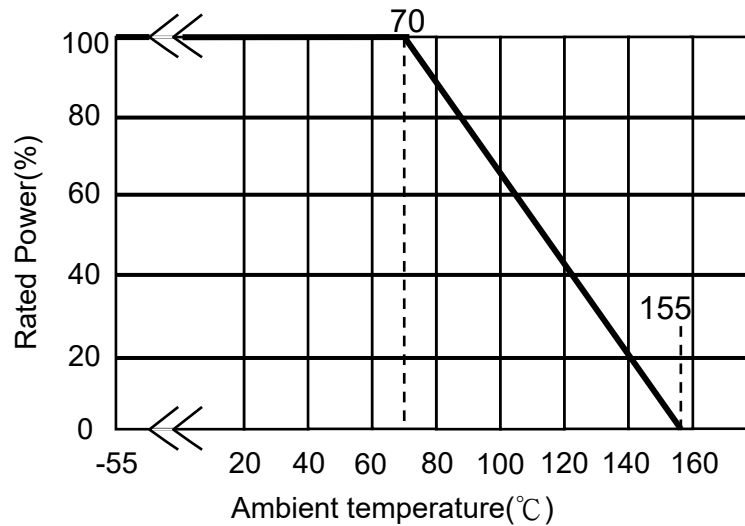
Type	Rated Power at 70°C	Max. Working Voltage	Max. Overload Voltage	T.C.R. (ppm/°C)	Resistance Range		Number of Terminals	Number of Resistors	JUMPER (0Ω) Rated Current	JUMPER (0Ω) Resistance Value		
					F(±1%) E-24 · E-96	J(±5%) E-24				J (±5%)		F(±1%)
					A	B				B		
RSA02-2D (0402)	1/16 W	25V	50V	±300	1Ω ≤ R < 10Ω	1Ω ≤ R < 10Ω	4	2	1A	50mΩ MAX.	100mΩ MAX.	50mΩ MAX.
				±200	10Ω ≤ R ≤ 10MΩ	10Ω ≤ R ≤ 10MΩ						
RSA03-2D (0603)	1/16 W	50V	100V	±200	10Ω ≤ R ≤ 10MΩ	1Ω ≤ R ≤ 10MΩ	4	2	1A	50mΩ MAX.	100mΩ MAX.	50mΩ MAX.
RSA02-4D (0402)	1/16 W	25V	50V	±300	1Ω ≤ R < 10Ω	1Ω ≤ R < 10Ω	8	4	1A	50mΩ MAX.	100mΩ MAX.	50mΩ MAX.
				±200	10Ω ≤ R ≤ 10MΩ	10Ω ≤ R ≤ 10MΩ						
RSA03-4D (0603)	1/16 W	50V	100V	±200	1Ω ≤ R ≤ 10MΩ	1Ω ≤ R ≤ 10MΩ	8	4	1A	50mΩ MAX.	100mΩ MAX.	50mΩ MAX.
Operating Temperature Range				-55°C ~ +155°C								

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3.1 Power Derating Curve:

Operating Temperature Range : - 55~155 °C

If the ambient temperature exceeds 70 degrees centigrade to 155 degrees centigrade, the power can be modified by the curve as below.



3.2 Voltage Rating:

Resistance Range:

Rated Voltage: DC voltage or AC voltage (rms) based on the rated power.

The voltage can be calculated by the following formula. If the calculated value exceeds the Max. voltage specified in the Table 3, the Max. voltage rating is set as the voltage rating.

$$E = \sqrt{R \times P}$$

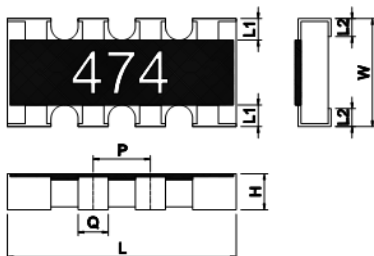
E= Rated voltage (V)

P= power rating (W)

R= Nominal resistance(Ω)

4 Structure Graph:

Unit:mm



TYPE	DIM	L	W	H	L1	L2	P	Q
RSA02-2D (0402)		1.00±0.10	1.00±0.10	0.30±0.05	0.15±0.10	0.25±0.15	(0.67)	0.33±0.10
RSA02-4D (0402)		2.00±0.10	1.00±0.10	0.40±0.10	0.20±0.10	0.25±0.15	(0.50)	0.30±0.10
RSA03-2D (0603)		1.60±0.15	1.60±0.15	0.45±0.10	0.30±0.15	0.30±0.20	(0.80)	0.60±0.10
RSA03-4D (0603)		3.20±0.20	1.60±0.15	0.50±0.10	0.30±0.15	0.30±0.20	(0.80)	0.50±0.10

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5 Reliability Test:

Item	Conditions	Specifications	
		Resistors	Jumper
High Temperature Exposure (Storage)	Put the specimens in the chamber with temperature of 155±3°C for 1000 hours. Then take them out to stabilize in room temperature for 24±4hr or more, and measure of its resistance variance rate. Experiment evidence: AEC-Q200	1.1% : ΔR=±1.0% 2.5% : ΔR=±2.0%	Refer to item 3. general specifications
Temperature Cycling	Put the specimens in the High & low temperature test chamber with temperature varies from -55°C to 125°C for 15 minutes and total 1000 cycles. Then take them out to stabilize in room temperature for 24±4hr or more, and measure of its resistance variance rate. Experiment evidence: AEC-Q200	ΔR=±2.0%	Refer to item 3. general specifications
Biased Humidity	Solder the specimens on the test PCB and put them into the constant temperature humidity chamber with 85±2°C and 85±5%RH. Then apply the test voltage that calculates based on the 10% of rated power for 1000hrs. Then take them out to stabilize in room temperature for 24±4hr or more, and measure of its resistance variance rate. Experiment evidence: AEC-Q200	1. 1% : ΔR=±2.0% 2.5% : ΔR=±3.0%	Refer to item 3. general specifications
Operational Life	Solder the specimens on the test PCB and Put them in the chamber with temperature of 125±3°C and load the voltage for 1000 hours. Then take them out to stabilize in room temperature for 24±4hr or more, and measure of its resistance variance rate. Note: The input voltage shall refer to the power de-rating curve (referring to page 2, No.3.1) Experiment evidence: AEC-Q200	1. 1% : ΔR=±2.0% 2.5% : ΔR=±3.0%	Refer to item 3. general specifications
Short Time Overload	Applied 2.5 times rated voltage for 5 seconds and release the load for about 30 minutes, then measure its resistance variance rate. (Rated voltage refer to item 3. general specifications) Refer to JIS-C5201-1 4.13	1. 1% : ΔR=±1.0% 2. 5% : ΔR=±2.0%	Refer to item 3. general specification
Resistance to Soldering Heat	The specimens are fully immersed into the Pb-free solder pot, then take them out to stabilize for 1 hour or more and measure of its resistance variance rate. Temp of solder pot : 260±5°C Soldering duration : 10±1sec. Experiment evidence AEC-Q200	ΔR=±1.0%	Refer to item 3. general specifications
ESD	Put the specimens on the test fixture and two (2) discharges (2KVDC) shall be applied to each PUT, one (1) with a positive polarity and one (1) with a negative polarity. Afterwards, the specimens stabilize for 30min or more and measure of its resistance variance rate. The test is performed with direct contact and regular discharge mode. The resistor and capacitor used on the spearhead is 2000Ω and 150pF respectively. Experiment evidence AEC-Q200	ΔR=±3.0%	Refer to item 3. general specifications

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Item	Conditions	Specifications	
		Resistors	Jumper
Solderability	<p>Test method: Test item 1 (solder pot test): Method B Precondition: The specimens are subjected to 155°C dry bake for 4hrs±15min. The specimens are immersed into the flux first, then fully immersed into the solder pot, at a temperature of 235±5°C for 5+0/-0.5 sec. Then rinse with water and observe the soldering coverage under the microscope. Test item 2 (Leaching test): Method D The specimens are immersed into the flux first, then fully immersed into the solder pot, at a temperature of 260±5°C for 30+0/-0.5 sec. Then rinse with water and observe the soldering coverage under the microscope. Experiment evidence AEC-Q200</p>	1.Soldering coverage over 95% 2. At the edge of terminal, the object underneath (e.g. white ceramic) shall not expose.	
Electrical Characterization	$TCR \text{ (ppm / } ^\circ\text{C)} = \frac{(R2 - R1)}{R1 (T2 - T1)} \times 10^6$ R1: Resistance at room temperature (Ω) R2: Resistance at -55°C or +125°C (Ω) T1: Room temperature (°C) T2: Temperature -55°C or +125°C Experiment evidence: AEC-Q200	Refer to item 3.general specifications	NA
Board Flex (Bending Test)	Solder the specimens on the test PCB and put the PCBA onto the Bending Tester. Add force at the central part of PCB, and the duration of the applied forces shall be 60 (+ 5) Sec. Measure of its resistance variance rate in load. Bending depth (D)=5mm Experiment evidence: AEC-Q200	ΔR=±1.0%	Refer to item 3.general specifications No mechanical damage, peeling off of side end or chip crack.
Sulfuration Test	Class : A	Put the tested resistor in sulfur vapor, at a temperature of 60±2°C for 1000hrs Refer to ASTM-B-809-95&EIA977	Refer to item 3. general specifications
	Class : B	Put the tested resistor in sulfur vapor, at a temperature of 105±2°C for 750hrs Refer to ASTM-B-809-95&EIA977	

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6 Plating Thickness:

6.1 Ni: $\geq 2\mu\text{m}$

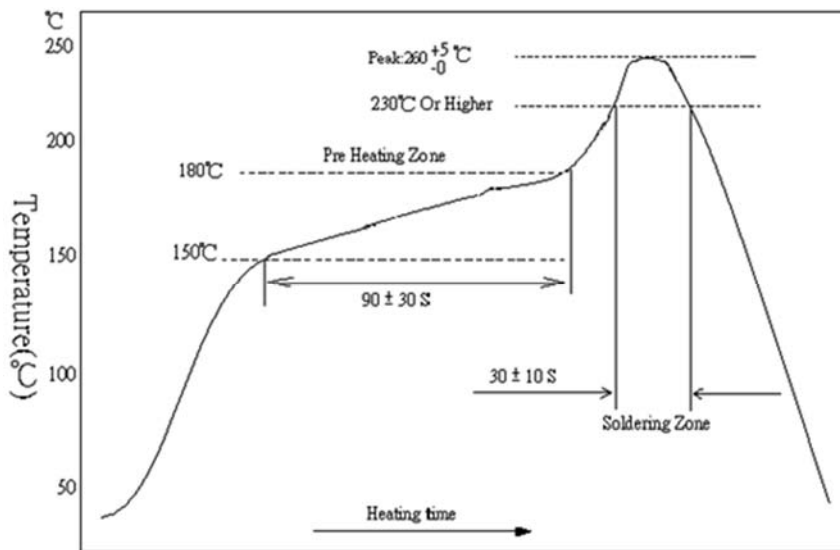
6.2 Sn(Tin): $\geq 3\mu\text{m}$

6.3 Sn(Tin): Matte Sn

7 Technical application notes: (This is for recommendation, please customer perform adjustment according to actual application)

7.1 Recommend Soldering Method:

7.1.1 Lead Free IR-Reflow Soldering Profile (MEET J-STD-020D)



Remark: The peak temperature of soldering heat is 260 +5/-0 °C for 10 seconds

7.1.2 Soldering Iron: temperature 350°C±10°C , dwell time shall be less than 3 sec

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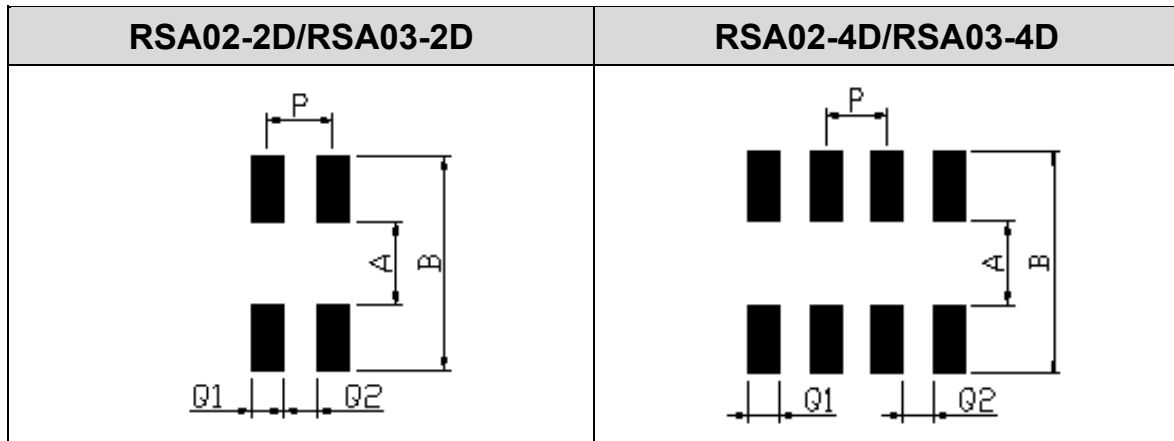
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7.2 Recommend Land Pattern Design (For Reflow Soldering):

When a component is soldered, the resistance after soldering changes slightly depending on the size of the soldering area and the amount of soldering. When designing a circuit, it is necessary to consider the effect of a decrease or increase in its resistance.

Unit:mm



DIM	A	B	P	Q1	Q2
RSA02-2D	0.50	2.00	0.67	0.33	0.34
RSA02-4D	0.50	2.00	0.50	0.28	0.22
RSA03-2D	1.00	2.60	0.80	0.40	0.40
RSA03-4D	1.00	2.60	0.80	0.40	0.40

7.3 Environment Precautions

This specification product is for general electronic use, RALEC will not be responsible for any damage, cost or loss caused by using this specification product in any special environment. If other applications need to confirm with RALEC.

If consumer intends to use our Company product in special environment or condition (including but not limited to those mentioned below), then will need to make individual recognition of product features and reliability accordingly.

- (a) Used in high temperature and humidity environment
- (b) Exposed to sea breeze or other corrosive gas, such as Cl₂、H₂S、NH₃、SO₂ and NO₂.
- (c) Used in non-verified liquids including water, oil, chemical and organic solvents.
- (d) Using non-verified resin or other coating material to seal or coat our Company product.
- (e) After soldering, it is necessary to use water-soluble detergents to clean residual solder fluxes, even though no-clean fluxes are recommended.

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7.4 Momentary Overload Precautions

The product might be out of function when momentary overloaded. Please make sure to avoid momentary overloading while using and preserving ◦

7.5 Operation and Processing Precautions

- (a) Avoid damage to the edge of resistor and protective layer caused by mechanical stress.
- (b) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
- (c) Make sure the power rating is under the limit when using the resistor. When power rating is over the limit, the resistor will be overloaded. There might be machinery damage due to the climbing temperature.
- (d) If the resistor will be exposed under massive impact load (shock wave) in a short period of time, the working environment must be set up well before use.
- (e) Please make evaluation and confirmation when the product is well used in your company and have a through consideration of it's fail-safe design to ensure the system safety.

8 Storage and transportation requirement:

- 8.1 The temperature condition must be controlled as $25\pm 5^{\circ}\text{C}$, the R.H. must be controlled as $60\pm 15\%$. The stock can maintain quality level in two years.
- 8.2 Please avoid the mentioned harsh environment below when storing to ensure product performance and its' weldability. Places exposed to sea breeze or other corrosive gas, such as Cl_2 、 H_2S 、 NH_3 、 SO_2 and NO_2 .
- 8.3 When the product is moved and stored, please ensure the correct orientation of the box. Do not drop or squeeze the box. Otherwise, the electrode or the body of the product may be damaged.



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10 Attachments:

10.1 Document Revise Record Paper(QA-QR-027)

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